

PATENT ASSIGNMENT

Electronic Version v1.1

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SUBMISSION TYPE:	NEW ASSIGNMENT						
NATURE OF CONVEYANCE:	ASSIGNMENT						
CONVEYING PARTY DATA							
<table border="1"><thead><tr><th>Name</th><th>Execution Date</th></tr></thead><tbody><tr><td>Wenzhi Gao</td><td>01/22/2007</td></tr><tr><td>Young Way Teh</td><td>01/18/2007</td></tr></tbody></table>	Name	Execution Date	Wenzhi Gao	01/22/2007	Young Way Teh	01/18/2007	
Name	Execution Date						
Wenzhi Gao	01/22/2007						
Young Way Teh	01/18/2007						
RECEIVING PARTY DATA							
Name:	Chartered Semiconductor Manufacturing, LTD.						
Street Address:	60 Woodlands Industrial Park D, Street Two						
City:	Singapore						
State/Country:	SINGAPORE						
Postal Code:	738406						
PROPERTY NUMBERS Total: 1							
<table border="1"><thead><tr><th>Property Type</th><th>Number</th></tr></thead><tbody><tr><td>Application Number:</td><td>11672572</td></tr></tbody></table>	Property Type	Number	Application Number:	11672572			
Property Type	Number						
Application Number:	11672572						
CORRESPONDENCE DATA							
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NAME OF SUBMITTER:	Yuanmin Cai						
Total Attachments: 2 source=FIS920060207US1_CharteredAssignment#page1.tif source=FIS920060207US1_CharteredAssignment#page2.tif							

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PATENT ASSIGNMENT FORM

For and in consideration of good and valuable consideration, the receipt and sufficiency thereof being hereby acknowledged, each undersigned inventor acknowledges his/her prior and ongoing obligation to sell, assign, and transfer, and agrees to sell, assign, and transfer the entire world wide right, title and interest for the United States and all foreign countries, in and to any and all inventions and improvements conceived during and within the scope of his/her employment, and further acknowledges that he/she has sold, assigned, and transferred, and hereby sells, assigns, and transfers, unto:

**CHARTERED SEMICONDUCTOR MANUFACTURING, LTD.
60 WOODLAND INDUSTRIAL PARK D, STREET TWO
SINGAPORE, SINGAPORE 738406**

a corporation of Singapore, and, **Chartered Semiconductor Manufacturing, LTD.** desires to acquire all right, title, and interest, in and to the certain inventions (identified below), applications, and any United States and foreign patents to be obtained therefor relating to:

**Title of Invention for A METHOD FOR IMPROVED FABRICATION OF A
SEMICONDUCTOR USING A STRESS PROXIMITY TECHNIQUE PROCESS**

United States Patent

as set forth in United States Patent Application executed by each undersigned inventor on the date indicated by each inventor signature below, and further identified by **Attorney Docket Number FIS920060207US1**;
(select one): ☒ executed concurrently herewith or ☐ Serial No. _____ Filed on _____

for and to said United States Patent Application including any and all divisions or continuations thereof and in and to any and all Letters Patent of the United States and foreign patents and all rights of priority to be obtained therefor which may issue on any such application or for said invention therein disclosed, including any and all reissues or extensions thereof, to be held and enjoyed by, its successors, legal representatives and assigns to the full end of the term or terms for which any and all such Letters Patent may be granted as fully and entirely as would have been held and enjoyed by the undersigned had this Assignment not been made;

Each undersigned inventor hereby authorizes and requests the Commissioner of Patents and Trademarks to issue any and all such Letters Patent to Chartered Semiconductor Manufacturing, LTD its successors and assigns, in accordance herewith;

Each undersigned inventor warrants and covenants that he/she has the full and unencumbered right to sell and assign the interests hereby sold and assigned and that he/she has not executed and will not execute any document or instrument in conflict herewith;

Each undersigned inventor further covenants and agrees that he/she, upon the request and at the expense of the Chartered Semiconductor Manufacturing, LTD., will execute and deliver any papers, make all rightful oaths, testify in any legal proceeding relating to said inventions and improvements, communicate to the Chartered Semiconductor Manufacturing, LTD. all facts known to the undersigned relating to such inventions and improvements and the history thereof; and perform all other lawful acts deemed necessary or desirable by Chartered Semiconductor Manufacturing, LTD., and its legal representatives, to secure, maintain, and enforce patent protection for such inventions and improvements and for vesting title to such inventions and improvements in the Chartered Semiconductor Manufacturing, LTD., and in particular to perfect title to said above-identified certain inventions, and applications including divisions and continuations thereof, and any and all Letters Patent which may be granted therefore or thereon, including reissues, extensions, or counterparts;


Each undersigned inventor hereby grants the Chartered Semiconductor Manufacturing, LTD. and the firm of the power to insert in this Assignment any further identification which may be necessary or desirable for recordation of this Assignment.

PATENT
DOCKET NO. FIS920060207US1

Executed by Inventor 1 of 2

Signature:  Date: 22/01/07
Wenzhi Gao

Executed by Inventor 2 of 2

Signature:  Date: 18/01/2007
Young Way Teh